MacDermid Alpha to be a Supporting Partner at the Upcoming IMAPS Device Packaging Conference

(Waterbury, CT USA) – March 30, 2021 – MacDermid Alpha Electronics Solutions, a global leader in high performance electronics materials, will be a Supporting Partner at the upcoming IMAPS Device Packaging Conference being held virtually from April 12-15, 2021. MacDermid Alpha will highlight their entire portfolio of technologies from their MacDermid Enthone, Alpha, Kester, and Compugraphics brands essential to advanced semiconductor packaging and the markets it enables.

Rich Retallick, Director of Electronics Specialties, Circuitry Solutions, co-authored the presentation "Active Mold Packaging for Novel RDL Formation in a Fan-In Ball Grid Array for Power Applications". The presentation can be viewed starting Tuesday, April 13 and will be On Demand for 30 days. Jim Watkowski, Vice President Innovation, Circuitry Solutions, will be part of the 5G Panelist Discussion, highlighting the benefits of Copper Adhesion Promotion for 5G. The session will take place on Thursday, April 15 1:00 – 3:00pm. All conference registrants will be able to take part in both the technical presentations as well as the 5G panel discussion.

On Tuesday, April 13, 5:00 – 6:00pm EST, MacDermid Alpha will be hosting a "Meet the Experts" open forum with technology experts from their Circuitry, Semiconductor, and Assembly Solutions divisions. This will be a great opportunity to speak to our panel of experts and to learn more about some of the latest offerings MacDermid Alpha has for the Semiconductor and IC Substrate Markets; including Systek UVF 100; a 2-in1 RDL via filling technology for IC substrates, and the Systek ETS 1200; an advanced DC acid copper pattern plating process specifically formulated for the construction of embedded trace substrates. The Alpha brand STAYDRY Z20 film, a unique getter which employs an active desiccant for water absorption dispersed in a flexible silicone polymer matrix and the Kester brand of Thermal Interface Materials used to enhance heat transfer across the interface between a heat source and heatsink will also be discussed. The session is by invitation only. If interested, please complete the contact us form linked here : Contact Us

For more information on MacDermid Alpha's semiconductor chemistries and assembly materials please visit MacDermidAlpha.com.

Contact:
Deanna Cullen
Marketing Communications Manager
Deanna.Cullen@MacDermidAlpha.com